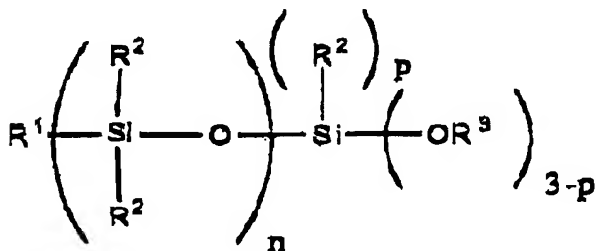


WHAT IS CLAIMED IS:

1. A liquid crystal sealing composition characterized by being an epoxy resin composition of one-component type comprising (1) an alkoxysilyl group-containing modified epoxy resin obtained by de-alcohol condensation reaction of (a) an epoxy resin having at least one hydroxyl group in one molecule and (b) an alkoxysilyl group-containing compound represented by formula (2):

[Formula 2]



wherein R^1 represents a C1 to C8 alkyl group, a phenyl group or a C1 to C8 alkenyl group, each of which may have a C1 to C8 alkoxy group, vinyl group, acryloyl group, methacryloyl group, carboxyl group, epoxy group, glycidyl group, amino group and mercapto group, R^2 represents a C1 to C8 alkoxysilyl group, a C1 to C8 alkyl group or a phenyl group, R^3 represents a C1 to C8 alkyl group, n is an integer of 0 to 6, and p is an integer of 0 to 2, (2) a heat latent epoxy curing agent and (3) a filler having an average particle diameter of 0.1 to 10 μm .

2. The liquid crystal sealing composition according to claim 1, further comprises (4) epoxy resin having at least 1.2 epoxy groups on average in one molecule.

3. The liquid crystal sealing composition according to claim 1 or 2, wherein the alkoxysilyl group-containing modified epoxy resin (1) is contained in an amount of 1 to 30% by weight based on 100% by weight of the liquid crystal sealing composition.

4. The liquid crystal sealing composition according to any one of claims 1 to 3, wherein at least one kind of the heat latent epoxy curing agent (2) is an amine-based heat latent curing agent, and its melting point or its softening temperature as determined by a ring and ball method is 100°C or more.

5. The liquid crystal sealing composition according to any one of claims 1 to 4, wherein at least one kind of the heat latent epoxy curing agent (2) described in claim 4 is an imidazole-based curing agent having a melting point of 130°C or more.

6. The liquid crystal sealing composition according to any one of claims 1 to 5, wherein the filler (3) is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid sealing composition.

7. The liquid crystal sealing composition according to any one of claims 1 to 6, wherein (5) an aprotic solvent compatible with epoxy resin and inert to an epoxy group and having a boiling point in the range of 140 to 220°C is contained in an amount of 5 to 30% by weight based on 100% by weight of the liquid crystal

sealing composition.

8. A method of producing a liquid crystal display panel, which comprises the heat cured liquid crystal sealing composition according to any one of claims 1 to 7.

9. A liquid crystal display panel produced by the method of producing a liquid crystal display panel according to claim 8.